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Generative AI for Analog/RF Integrated Circuit Design and Netlist Synthesis: Evolving Methodologies and Emerging Applications

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This paragraph of the first footnote will contain support information, including sponsor and financial support acknowledgment. For example, "This work was supported in part by the U.S. Department of Commerce under Grant BS123456."

ABSTRACT Electronic Design Automation (EDA) in analog Integrated Circuits (ICs) continues to be a critical research area, yet its widespread adoption significantly lags behind its digital counterpart due to inherent complexities. This extended systematic review updates recent contributions in the last five years, specifically highlighting cutting-edge methods that address persistent domain-specific challenges such as data scarcity, efficient topology exploration, robust parameter optimization considering process-voltage-temperature (PVT) variations, and accurate layout parasitic management. Our primary objective is to equip researchers new to this rapidly evolving domain with a comprehensive collection of references, a refined understanding of current challenges, and practical application guidelines. We provide an in-depth methodological review of state-of-the-art machine learning (ML) and generative AI approaches—including Graph Neural Networks (GNNs), Large Language Models (LLMs), and Variational Autoencoders (VAEs)—which are increasingly applied across various analog circuit design tasks, from topology synthesis to parameter sizing and validation. Notably, this survey expands on previous works by integrating discussions on newer, comprehensive frameworks like FALCON and MenTeR, which introduce end-to-end design, multi-agent workflows, and advanced layout-aware optimization. To the best of the authors' knowledge, this is the second review after [1] to comprehensively explore these latest applications of generative AI models in analog IC circuit design, charting their evolution and impact. We conclude by identifying key future research directions, emphasizing few-shot learning, multi-modal AI, and advanced multi-agent systems to further simplify human-tool interaction and guide design space exploration for industrial-scale analog ICs.

INDEX TERMS Analog integrated circuits (ICs), electronic design automation (EDA), generative artificial intelligence (GenAI), graph neural networks (GNNs), large language models (LLMs), machine learning (ML), netlist synthesis, parameter optimization, layout-aware sizing, topology synthesis, variational autoencoders (VAEs).

I. INTRODUCTION

THE escalating complexity and diverse performance requirements of modern analog systems underpin advancements in crucial technologies such as generative AI, 5G/6G communication, and quantum computing. *"analog genie"* These demands necessitate full-flow automation to effectively manage the intricate trade-offs between numerous performance parameters, a task where traditional manual approaches are notoriously time-consuming and heavily reliant on scarce expert knowledge. While digital design automation has witnessed extensive development and widespread adoption across both industry and academia, the automation of analog IC design continues to face significant challenges.

Researchers have made concerted efforts to automate various stages of the analog design flow*"genAI paper"*. Conventionally, the process is segmented into three primary areas at the circuit level: topology selection, circuit sizing, and layout generation, often with complex feedback loops, as clearly shown in Fig. 1. Although remarkable progress has been achieved in layout generation tools, such as MAGICAL and ALIGN, and in certain aspects of digital IC design with generative AI, the development of scalable and robust solutions for analog circuit sizing and comprehensive topology design remains a formidable challenge. Furthermore, a truly practical automation flow at each stage must inherently account for the interdependencies across design stages*"5,6,7 from genAI paper"*; for instance, the initial selection of a topology must proactively consider potential layout parasitics and their subsequent impact on performance metrics.

The fundamental challenge arises from the intricate design complexities of analog ICs. Unlike digital ICs that can be universally and hierarchically abstracted into Boolean logic representations and easily described with high-level hardware description languages (e.g., Verilog and VHDL) or programming languages (e.g., C), analog ICs remain intractable to such abstraction due to their lack of systematic hierarchical representation and the heuristic and knowledge-intensive nature of their design process [1]. This makes automating analog IC design using programming languages similar to those for digital ICs extremely difficult. As such, domain experts have followed a longstanding manual flow to design analog ICs. This process involves a number of time-consuming stages, such as selecting/creating an existing (new) circuit topology (i.e., defining the connections between devices), optimizing device parameters based on the topology to achieve desired performance, and designing the physical layout of the optimized circuit for manufacturing. Importantly, the topology generation stage is the foundation and most creative part of the analog IC design process, posing a formidable and perennial challenge to design automation. Addressing it is the key to accelerating the development of analog ICs.

In response to these challenges, machine learning (ML) has emerged as a promising solution. Learning-based methods, which leverage simulation data for training, offer more efficient design space exploration. ML techniques can be applied individually or in combination to facilitate decision-making, function approximation, and black-box optimization. Recent breakthroughs in generative AI, a subset of ML, have presented transformative opportunities to expedite these conventional design flows. Models such as Graph Neural Networks (GNNs) have shown significant advantages for handling graph-structured circuit data, while Variational Autoencoders (VAEs) are being explored to learn underlying data distributions for tasks like topology optimization. Furthermore, Large Language Models (LLMs), traditionally used for natural language processing, have demonstrated remarkable adaptability to large-scale design problems, including layout automation, optimization, and topology generation.

Despite these advances, many prior studies on ML-driven analog circuit design have often focused on isolated subtasks or simple, homogeneous circuits, overlooking the complexities of real-world heterogeneous systems. *"AI Circuit,* The persistent lack of comprehensive, generic, and diverse datasets with robust metrics has been a major impediment to thoroughly evaluating and improving ML algorithms in the analog domain. Moreover, many early generative AI approaches for topology generation were limited in scale, producing single types of small or conventional ICs, or suffered from ambiguous representations. This has encouraged the recent works to try bridging these gaps by proposing more holistic frameworks that integrate multiple design stages, leverage multi-agent systems, and incorporate layout-aware optimization to better reflect practical design scenarios. *"AI Circuit, FALCON, MenTeR "ADO-LLM", "Analog-GENIE", "AMP-AGENT"*

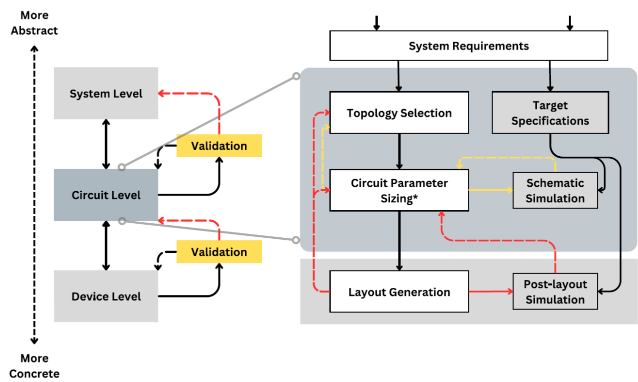

FIGURE 1. Analog design automation flow, focusing on circuit-level automation. Dashed lines indicate dependencies between design stages.

This paper aims to bridge these gaps by providing an updated and expanded systematic review of generative AI applications in analog IC design. We particularly focus on recent developments that push the boundaries of automation across the entire design pipeline, addressing shortcomings such as data scarcity, limited scalability, and inadequate layout awareness. Specifically, this review will integrate analysis of groundbreaking new frameworks like:

- **AnalogGenie**: A generative engine focused on the automatic discovery of diverse, large, and unseen analog circuit topologies using a scalable sequence-based graph representation and an augmented dataset.
- **AnalogCoder**: The first training-free LLM agent that designs analog circuits through Python code generation, employing feedback-enhanced flows and a circuit tool library.
- **SPICEPilot**: A framework leveraging LLMs to generate Python-based SPICE code, addressing data scarcity by automating dataset creation and providing standardized benchmarking.
- **AnalogXpert**: An LLM-based agent for subcircuit-level SPICE code generation that incorporates circuit design expertise through a proofreading strategy for iterative error correction.
- **MenTeR**: A fully-automated multi-agent workflow for end-to-end RF/Analog circuit netlist design, emphasizing specification understanding, collaborative optimization, and test bench validation through Chain-of-Stage reasoning and Diagram-Aware RAG.
- **FALCON**: A unified ML framework enabling fully automated, specification-driven analog circuit synthesis through performance-driven topology selection, GNN-

based parameter inference, and layout-constrained optimization, validated with industrial-grade simulations.
- **AICircuit**: A multi-level dataset and benchmark that facilitates the development and evaluation of ML algorithms for both homogeneous and heterogeneous analog and RF circuit designs.

These frameworks represent significant strides toward achieving holistic, human-competitive, and even superhuman capabilities in analog IC design.

The main contributions of this paper are as follows:

- **Comprehensive Survey of Recent Advancements**: Examine and compare recent advancements in generative AI for analog circuit design, with a particular focus on evolving techniques that address topology exploration, scalable parameter sizing, robust PVT variations, and realistic layout parasitics.
- **Methodological Review of State-of-the-Art Techniques**: Provide a methodological review of state-of-the-art generative AI techniques applied in analog circuit design automation, including Graph Neural Networks (GNNs), Large Language Models (LLMs), and Variational Autoencoders (VAEs), showcasing their latest applications and interconnections.
- **Analysis of Novel Comprehensive Frameworks**: Integrate and analyze new, comprehensive frameworks such as FALCON, MenTeR, AnalogGenie, AnalogCoder, SPICEPilot, and AnalogXpert, which were not thoroughly covered in previous surveys, providing insights into their unique contributions and synergistic potential.
- **Practical Resource Compilation**: Collect and synthesize abundant resources, open-source codes, and application guidelines to serve as a practical reference for researchers new to or advancing within the field of analog circuit automation.

The remainder of this paper is structured as follows: section II summarizes and compares previous review papers in terms of their automation scope and the ML techniques covered, highlighting the gaps addressed by this work. section III introduces fundamental IC design challenges and outlines how these challenges shape the automation task for generative AI. section IV provides the fundamentals of generative AI relevant to recent research, including detailed discussions on GNNs, LLMs, and VAEs. section V comprehensively compares significant research works, focusing on their methodologies, key problems they attempt to solve, and their contributions to the evolving landscape of analog design automation. Finally, section VI outlines future research directions and challenges for large-scale industrial adoption, including discussions on multi-agent systems and multi-modal AI.

II. RELATED WORKS

Use either SI (MKS) or CGS as primary units. (SI units are strongly encouraged.) English units may be used as secondary units (in parentheses). This applies to papers in data storage. For example, write "15 Gb/cm^2 (100 Gb/in^2)." An exception is when English units are used as identifiers in trade, such as "3$^{1/2}$-in disk drive." Avoid combining SI and CGS units, such as current in amperes and magnetic field in oersteds. This often leads to confusion because equations do not balance dimensionally. If you must use mixed units, clearly state the units for each quantity in an equation.

The SI unit for magnetic field strength H is A/m. However, if you wish to use units of T, either refer to magnetic flux density B or magnetic field strength symbolized as $\mu_0 H$. Use the center dot to separate compound units, e.g., "A·m^2."

A. EQUATIONS

Number equations consecutively with equation numbers in parentheses flush with the right margin, as in (1). To make your equations more compact, you may use the solidus (/), the exp function, or appropriate exponents. Use parentheses to avoid ambiguities in denominators. Punctuate equations when they are part of a sentence, as in

$$E = mc^2. \tag{1}$$

The following 2 equations are used to test your LaTeX compiler's math output. Equation (2) is your LaTeX compiler' output. Equation (3) is an image of what (2) should look like. Please make sure that your equation (2) matches (3) in terms of symbols and characters' font style (Ex: italic/roman).

$$\frac{47i + 89jk \times 10rym \pm 2npz}{(6XYZ\pi Ku)Aoq\sum_{i=1}^{r} Q(t)} \int_0^\infty f(g)\mathrm{d}x \sqrt[3]{\frac{abcdelqh^2}{(svw)\cos^3\theta}}. \tag{2}$$

$$\frac{47i + 89jk \times 10rym \pm 2npz}{(6XYZ\pi Ku)Aoq\sum_{i=1}^{r} Q(t)} \int_0^\infty f(g)\mathrm{d}x \sqrt[3]{\frac{abcdelqh^2}{(svw)\cos^3\theta}}. \tag{3}$$

Be sure that the symbols in your equation have been defined before the equation appears or immediately following. Italicize symbols (T might refer to temperature, but T is the unit tesla). Refer to "(1)," not "Eq. (1)" or "equation (1)," except at the beginning of a sentence: "Equation (1) is . . . ."

B. LATEX-SPECIFIC ADVICE

Please use "soft" (e.g., `\eqref{Eq}`) cross references instead of "hard" references (e.g., `(1)`). That will make it possible to combine sections, add equations, or change the order of figures or citations without having to go through the file line by line.

Please don't use the `{eqnarray}` equation environment. Use `{align}` or `{IEEEeqnarray}` instead. The `{eqnarray}` environment leaves unsightly spaces around relation symbols.

Please note that the `{subequations}` environment in LaTeX will increment the main equation counter even when there are no equation numbers displayed. If you forget that, you might write an article in which the equation numbers skip from (17) to (20), causing the copy editors to wonder if you've discovered a new method of counting.

BibTEX does not work by magic. It doesn't get the bibliographic data from thin air but from .bib files. If you use BibTEX to produce a bibliography you must send the .bib files.

LATEX can't read your mind. If you assign the same label to a subsubsection and a table, you might find that Table I has been cross referenced as Table IV-B3.

LATEX does not have precognitive abilities. If you put a `\label` command before the command that updates the counter it's supposed to be using, the label will pick up the last counter to be cross referenced instead. In particular, a `\label` command should not go before the caption of a figure or a table.

Do not use `\nonumber` inside the `{array}` environment. It will not stop equation numbers inside `{array}` (there won't be any anyway) and it might stop a wanted equation number in the surrounding equation.

III. SOME COMMON MISTAKES

The word "data" is plural, not singular. The subscript for the permeability of vacuum μ_0 is zero, not a lowercase letter "o." The term for residual magnetization is "remanence"; the adjective is "remanent"; do not write "remnance" or "remnant." Use the word "micrometer" instead of "micron." A graph within a graph is an "inset," not an "insert." The word "alternatively" is preferred to the word "alternately" (unless you really mean something that alternates). Use the word "whereas" instead of "while" (unless you are referring to simultaneous events). Do not use the word "essentially" to mean "approximately" or "effectively." Do not use the word "issue" as a euphemism for "problem." When compositions are not specified, separate chemical symbols by en-dashes; for example, "NiMn" indicates the intermetallic compound $Ni_{0.5}Mn_{0.5}$ whereas "Ni–Mn" indicates an alloy of some composition Ni_xMn_{1-x}.

Be aware of the different meanings of the homophones "affect" (usually a verb) and "effect" (usually a noun), "complement" and "compliment," "discreet" and "discrete," "principal" (e.g., "principal investigator") and "principle" (e.g., "principle of measurement"). Do not confuse "imply" and "infer."

Prefixes such as "non," "sub," "micro," "multi," and "ultra" are not independent words; they should be joined to the words they modify, usually without a hyphen. There is no period after the "et" in the Latin abbreviation "*et al.*" (it is also italicized). The abbreviation "i.e.," means "that is," and the abbreviation "e.g.," means "for example" (these abbreviations are not italicized).

A general IEEE styleguide is available at http://www.ieee.org/authortools.

IV. GUIDELINES FOR GRAPHICS PREPARATION AND SUBMISSION

A. TYPES OF GRAPHICS

The following list outlines the different types of graphics published in IEEE journals. They are categorized based on their construction, and use of color/shades of gray:

TABLE 1. Units for Magnetic Properties

Symbol	Quantity	Conversion from Gaussian and CGS EMU to SI [a]
Φ	magnetic flux	1 Mx $\rightarrow 10^{-8}$ Wb $= 10^{-8}$ V·s
B	magnetic flux density, magnetic induction	1 G $\rightarrow 10^{-4}$ T $= 10^{-4}$ Wb/m^2
H	magnetic field strength	1 Oe $\rightarrow 10^3/(4\pi)$ A/m
m	magnetic moment	1 erg/G = 1 emu $\rightarrow 10^{-3}$ A·m^2 $= 10^{-3}$ J/T
M	magnetization	1 erg/(G·cm^3) = 1 emu/cm^3 $\rightarrow 10^3$ A/m
$4\pi M$	magnetization	1 G $\rightarrow 10^3/(4\pi)$ A/m
σ	specific magnetization	1 erg/(G·g) = 1 emu/g $\rightarrow$ 1 A·m^2/kg
j	magnetic dipole moment	1 erg/G = 1 emu $\rightarrow 4\pi \times 10^{-10}$ Wb·m
J	magnetic polarization	1 erg/(G·cm^3) = 1 emu/cm^3 $\rightarrow 4\pi \times 10^{-4}$ T
χ, κ	susceptibility	$1 \rightarrow 4\pi$
χ_ρ	mass susceptibility	1 cm^3/g $\rightarrow 4\pi \times 10^{-3}$ m^3/kg
μ	permeability	$1 \rightarrow 4\pi \times 10^{-7}$ H/m $= 4\pi \times 10^{-7}$ Wb/(A·m)
μ_r	relative permeability	$\mu \rightarrow \mu_r$
w, W	energy density	1 erg/cm^3 $\rightarrow 10^{-1}$ J/m^3
N, D	demagnetizing factor	$1 \rightarrow 1/(4\pi)$

Vertical lines are optional in tables. Statements that serve as captions for the entire table do not need footnote letters.

[a]Gaussian units are the same as cg emu for magnetostatics; Mx = maxwell, G = gauss, Oe = oersted; Wb = weber, V = volt, s = second, T = tesla, m = meter, A = ampere, J = joule, kg = kilogram, H = henry.

1) Color/Grayscale figures

Figures that are meant to appear in color, or shades of black/gray. Such figures may include photographs, illustrations, multicolor graphs, and flowcharts. For multicolor graphs, please avoid any gray backgrounds or shading, as well as screenshots, instead export the graph from the program used to collect the data.

2) Line Art figures

Figures that are composed of only black lines and shapes. These figures should have no shades or half-tones of gray, only black and white.

3) Author photos

Author photographs should be included with the author biographies located at the end of the article underneath References.

4) Tables

Data charts which are typically black and white, but sometimes include color.

B. MULTIPART FIGURES

Figures compiled of more than one sub-figure presented side-by-side, or stacked. If a multipart figure is made up of multiple figure types (one part is lineart, and another is grayscale or color) the figure should meet the stricter guidelines.

C. FILE FORMATS FOR GRAPHICS

Format and save your graphics using a suitable graphics processing program that will allow you to create the images as

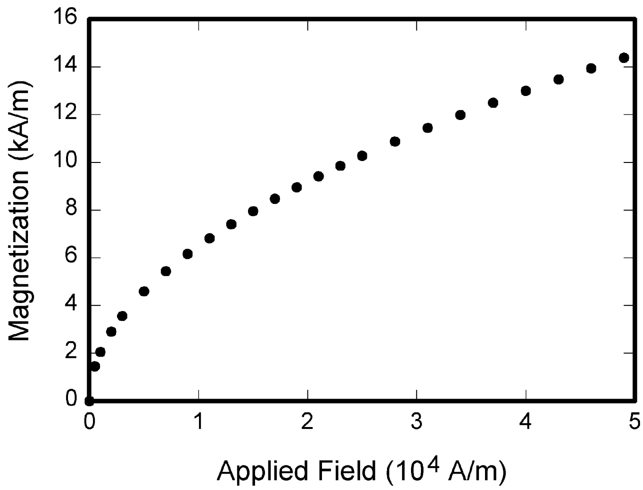

FIGURE 2. Magnetization as a function of applied field. It is good practice to explain the significance of the figure in the caption.

PostScript (.PS), Encapsulated PostScript (.EPS), Tagged Image File Format (.TIFF), Portable Document Format (.PDF), Portable Network Graphics (.PNG), or Metapost (.MPS), sizes them, and adjusts the resolution settings. When submitting your final paper, your graphics should all be submitted individually in one of these formats along with the manuscript.

D. SIZING OF GRAPHICS

Most charts, graphs, and tables are one column wide (3.5 inches/88 millimeters/21 picas) or page wide (7.16 inches/181 millimeters/43 picas). The maximum depth a graphic can be is 8.5 inches (216 millimeters/54 picas). When choosing the depth of a graphic, please allow space for a caption. Figures can be sized between column and page widths if the author chooses, however it is recommended that figures are not sized less than column width unless when necessary.

There is currently one publication with column measurements that do not coincide with those listed above. Proceedings of the IEEE has a column measurement of 3.25 inches (82.5 millimeters/19.5 picas).

The final printed size of author photographs is exactly 1 inch wide by 1.25 inches tall (25.4 millimeters $\times$ 31.75 millimeters/6 picas $\times$ 7.5 picas). Author photos printed in editorials measure 1.59 inches wide by 2 inches tall (40 millimeters $\times$ 50 millimeters/9.5 picas $\times$ 12 picas).

E. RESOLUTION

The proper resolution of your figures will depend on the type of figure it is as defined in the ‘‘Types of Figures’’ section. Author photographs, color, and grayscale figures should be at least 300dpi. Line art, including tables should be a minimum of 600dpi.

F. VECTOR ART

In order to preserve the figures' integrity across multiple computer platforms, we accept files in the following formats: .EPS/.PDF/.PS. All fonts must be embedded or text converted to outlines in order to achieve the best-quality results.

G. COLOR SPACE

The term color space refers to the entire sum of colors that can be represented within the said medium. For our purposes, the three main color spaces are Grayscale, RGB (red/green/blue) and CMYK (cyan/magenta/yellow/black). RGB is generally used with on-screen graphics, whereas CMYK is used for printing purposes.

All color figures should be generated in RGB or CMYK color space. Grayscale images should be submitted in Grayscale color space. Line art may be provided in grayscale OR bitmap colorspace. Note that ‘‘bitmap colorspace’’ and ‘‘bitmap file format’’ are not the same thing. When bitmap color space is selected, .TIF/.TIFF/.PNG are the recommended file formats.

H. ACCEPTED FONTS WITHIN FIGURES

When preparing your graphics IEEE suggests that you use of one of the following Open Type fonts: Times New Roman, Helvetica, Arial, Cambria, and Symbol. If you are supplying EPS, PS, or PDF files all fonts must be embedded. Some fonts may only be native to your operating system; without the fonts embedded, parts of the graphic may be distorted or missing.

A safe option when finalizing your figures is to strip out the fonts before you save the files, creating ‘‘outline’’ type. This converts fonts to artwork what will appear uniformly on any screen.

I. USING LABELS WITHIN FIGURES

1) Figure Axis labels

Figure axis labels are often a source of confusion. Use words rather than symbols. As an example, write the quantity ‘‘Magnetization,’’ or ‘‘Magnetization M,’’ not just ‘‘M.’’ Put units in parentheses. Do not label axes only with units. As in Fig. 1, for example, write "Magnetization (A/m)" or "Magnetization (A·m^{-1})," not just "A/m." Do not label axes with a ratio of quantities and units. For example, write "Temperature (K)," not "Temperature/K."

Multipliers can be especially confusing. Write "Magnetization (kA/m)" or "Magnetization (10^3 A/m)." Do not write "Magnetization (A/m) × 1000" because the reader would not know whether the top axis label in Fig. 1 meant 16000 A/m or 0.016 A/m. Figure labels should be legible, approximately 8 to 10 point type.

2) Subfigure Labels in Multipart Figures and Tables

Multipart figures should be combined and labeled before final submission. Labels should appear centered below each subfigure in 8 point Times New Roman font in the format of (a) (b) (c).

J. FILE NAMING

Figures (line artwork or photographs) should be named starting with the first 5 letters of the author's last name. The next characters in the filename should be the number that represents the sequential location of this image in your article. For example, in author "Anderson's" paper, the first three figures would be named ander1.tif, ander2.tif, and ander3.ps.

Tables should contain only the body of the table (not the caption) and should be named similarly to figures, except that '.t' is inserted in-between the author's name and the table number. For example, author Anderson's first three tables would be named ander.t1.tif, ander.t2.ps, ander.t3.eps.

Author photographs should be named using the first five characters of the pictured author's last name. For example, four author photographs for a paper may be named: oppen.ps, moshc.tif, chen.eps, and duran.pdf.

If two authors or more have the same last name, their first initial(s) can be substituted for the fifth, fourth, third. . . letters of their surname until the degree where there is differentiation. For example, two authors Michael and Monica Oppenheimer's photos would be named oppmi.tif, and oppmo.eps.

K. REFERENCING A FIGURE OR TABLE WITHIN YOUR PAPER

When referencing your figures and tables within your paper, use the abbreviation "Fig." even at the beginning of a sentence. Figures should be numbered with Arabic Numerals. Do not abbreviate "Table." Tables should be numbered with Roman Numerals.

L. SUBMITTING YOUR GRAPHICS

Figures should be submitted individually, separate from the manuscript in one of the file formats listed above in Section IV-C. Place figure captions below the figures; place table titles above the tables. Please do not include captions as part of the figures, or put them in "text boxes" linked to the figures. Also, do not place borders around the outside of your figures.

M. COLOR PROCESSING/PRINTING IN IEEE JOURNALS

All IEEE Transactions, Journals, and Letters allow an author to publish color figures on IEEE *Xplore*® at no charge, and automatically convert them to grayscale for print versions. In most journals, figures and tables may alternatively be printed in color if an author chooses to do so. Please note that this service comes at an extra expense to the author. If you intend to have print color graphics, include a note with your final paper indicating which figures or tables you would like to be handled that way, and stating that you are willing to pay the additional fee.

V. CONCLUSION

Although a conclusion may review the main points of the paper, do not replicate the abstract as the conclusion. A conclusion might elaborate on the importance of the work or suggest applications and extensions.

If you have multiple appendices, use the \appendices command below. If you have only one appendix, use \appendix[Appendix Title]

APPENDIX A
FOOTNOTES

Number footnotes separately in superscript numbers.[1] Place the actual footnote at the bottom of the column in which it is cited; do not put footnotes in the reference list (endnotes). Use letters for table footnotes (see Table 1).

APPENDIX B
SUBMITTING YOUR PAPER FOR REVIEW

A. FINAL STAGE

When your article is accepted, you can submit the final files, including figures, tables, and photos, per the journal's guidelines through the submission system used to submit the articlle. You may use *Zip* for large files, or compress files using *Compress, Pkzip, Stuffit,* or *Gzip.*

In addition, designate one author as the "corresponding author." This is the author to whom proofs of the paper will be sent. Proofs are sent to the corresponding author only.

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Article contributions to IEEE Access should be submitted electronically on the IEEE Author Portal. For more information, please visit https://ieeeaccess.ieee.org/.

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[1] It is recommended that footnotes be avoided (except for the unnumbered footnote with the receipt date on the first page). Instead, try to integrate the footnote information into the text.

The manuscript should be prepared in a double column, single-spaced format using a required IEEE Access template. A Word or LaTeX file and a PDF file are both required upon submission in the IEEE Author Portal.

C. FINAL STAGE USING IEEE AUTHOR PORTAL

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APPENDIX D
PUBLICATION PRINCIPLES

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1) Technical papers submitted for publication must advance the state of knowledge and must cite relevant prior work.
2) The length of a submitted paper should be commensurate with the importance, or appropriate to the complexity, of the work. For example, an obvious extension of previously published work might not be appropriate for publication or might be adequately treated in just a few pages.
3) Authors must convince both peer reviewers and the editors of the scientific and technical merit of a paper; the standards of proof are higher when extraordinary or unexpected results are reported.
4) Because replication is required for scientific progress, papers submitted for publication must provide sufficient information to allow readers to perform similar experiments or calculations and use the reported results. Although not everything need be disclosed, a paper must contain new, useable, and fully described information. For example, a specimen's chemical composition need not be reported if the main purpose of a paper is to introduce a new measurement technique. Authors should expect to be challenged by reviewers if the results are not supported by adequate data and critical details.
5) Papers that describe ongoing work or announce the latest technical achievement, which are suitable for presentation at a professional conference, may not be appropriate for publication.

APPENDIX E
REFERENCE EXAMPLES

- *Basic format for books:*
  J. K. Author, "Title of chapter in the book," in *Title of His Published Book, x*th ed. City of Publisher, (only U.S. State), Country: Abbrev. of Publisher, year, ch. *x*, sec. *x*, pp. *xxx–xxx.*
  See [1], [2].
- *Basic format for periodicals:*
  J. K. Author, "Name of paper," *Abbrev. Title of Periodical*, vol. *x, no. x* ,pp. *xxx–xxx,* Abbrev. Month, year, DOI. 10.1109.*XXX*.123456.
  See [3]– [5].
- *Basic format for reports:*
  J. K. Author, "Title of report," Abbrev. Name of Co., City of Co., Abbrev. State, Country, Rep. *xxx*, year.
  See [6], [7].
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